Messrs. Digi-Key

Issue No.	: PC-02-062
Date of issue	: November 15, 2002
Classification	: ■ New □ Change □ Renewal

Delivery Specification

: Balun
: EHF2BD2060
: Individual Product Specification
: Cellular phone
For other applications, contact the undersigned in advance.
: November 14, 2007 from the date of issue.

CUSTOMER USE ONLY	Receipt Record#:
This was certainly received by us. 1(one) copy is being returned to you.	Date of receipt:
r(one) copy to being retained to you.	Received by:
	Title: Dept.:

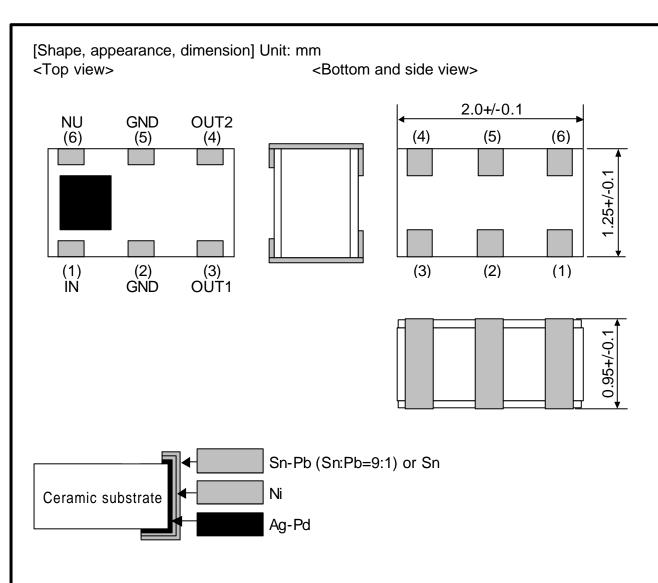
Matsushita Electronic Components Co., Ltd. Network Device Company Module Strategic Business Unit Engineering Group HFD Team

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Tel: +81-0585-36-2322 Fax: +81-0585-36-2344 Prepared by : H. Ito Checked by : M. Mizuno

Authorized by : M. Mizuno

Title : Manager of Engineering



Note 1) "typ" is used where no dimensional tolerance applies.

Item	Description				
Appearance/ construction	Product surface shall be covered with a protective film, which does not easily separate nor present noticeable unevenness, scratches, pinholes, color changes etc.				
	Terminals shall ensure practically acceptable quality.				
	Substrate shall be as shown in the drawing with no excessive chippings, scratches, burrs, or cracks.				
Marking	Shall be legible in black (with printing paste).				
Remarks	marked side for pin 1.				

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[Absolute maximum ratings]

No.	Item	Symbol	Rating	Unit	Remarks
1	Maximum input power	Pmax	100	mW	DC voltage is 0V.
2	Operating temperature	Topr	-30+85	degC	
3	Storage temperature	Tstg	-40+85	degC	

Note: This component cannot apply a DC Bias.

[Electrical characteristics]

T=-30...+85degC

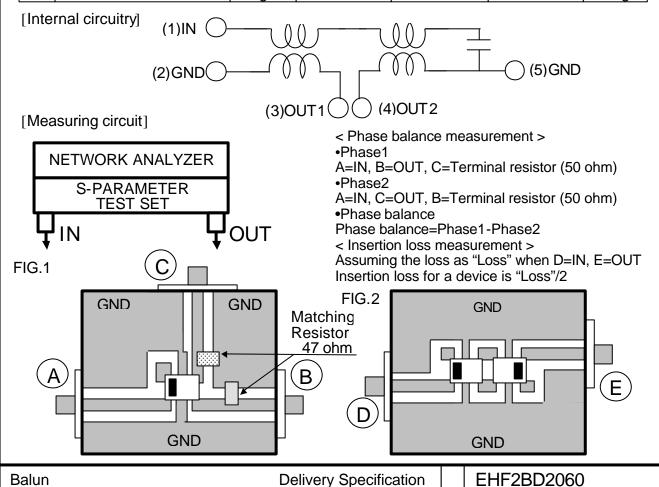
Specification and measurement

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151-EHF-2BD2060

Drawing No.

No.	Item	Test		Specification					
		Circuit	Min.	Тур.	Max.				
1	Frequency	ı	1920	-	2170	MHz			
2	Insertion loss (Back to back)	Fig-2	1	-	1.0	dB			
3	Unbalance impedance	ı	-	50	-	ohm			
4	Balance impedance	ı	-	50	-	ohm			
5	Unbalance port VSWR	Fig-1	-	-	2.0	-			
6	Amplitude balance	Fig-1	-1.5	_	1.5	dB			
7	Phase balance	Fig-1	165	180	195	deg			



P.S.M

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Approval

M. Mizuno

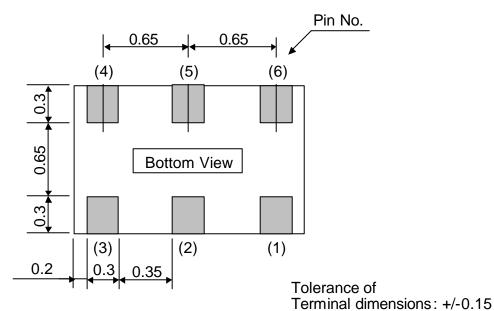
Check

M. Mizuno

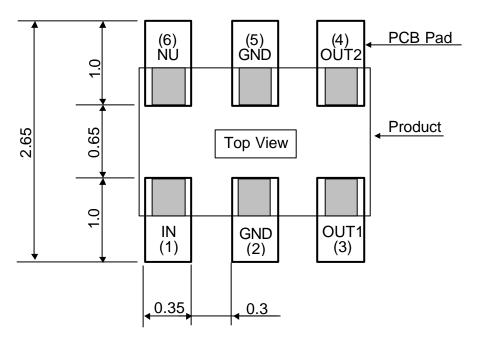
H. Ito

[Terminal dimensions] Unit: mm

<Bottom>



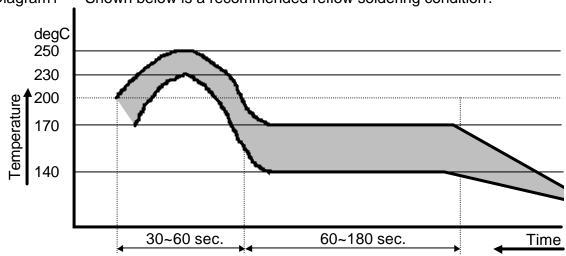
[Recommended PCB pad dimensions] Unit: mm



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[Quality characteristics	s]	
Test item	Test condition	Judgment criteria
High temperature	+85degC, 1000h	No abnormality shall be observed in
Low temperature	-40degC, 1000 h	appearance or
High-temperature high-humidity storage	+60degC, 90%RH, 1000h	electrical characteristics.
Pressure Pot	+121degC, 99%RH, 2.026x10 ⁵ Pa, 100h	Characteristics.
Temperature cycling	-40+85degC, Each 30 min., 200cy	
Vibration	10500Hz, 10G, in each direction of XYZ, 2h30min.	
Impact	100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times	
Shock (Drop)	1.8m, 6 facesx6cy(36 times with 100g Dummy Load)	
Electro static discharge	200pF, 0 ohm, +/-200V, Each 5 times	
Soldering heat resistance	Manual hot gas: 260+/-10degC, 30 sec., 2 times	Over 90% of the terminal surface shall be covered
	Soldering iron: 260+/-10degC, 3 sec., 2 times	with solder.
	Reflow: 260degC peak, 2 times	
Solder ability	Solder bath: 235+/-5degC, 2 sec.	Over 95% of the terminal surface shall be covered
	Reflow: 230degC	with solder.
Board warping	Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. 45mm 45mm 45mm	There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics.
Terminal removal	Solder a component on a PC board using the recommended of then press the component sideways at 1mm/sec. Destruction lin	
Seating plane co-planarity	Within 0.1mm	





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[Cautions for use]

- (1) Operating a product over the maximum rating for even a moment may result in a product failure or breakage. Never use a product in such a condition that it may cause a safety problem.
- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as high-temperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC voltage between the Balance port and the Unbalance port may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

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[Packaging materials] 1. Materials 1)

- 1) Embossed carrier tape (Refer to the attachment)
 2) Top tape: Anti-static

- 3) Packaging box (Refer to the attachment)4) Packaging tape, carrier-securing adhesive tape

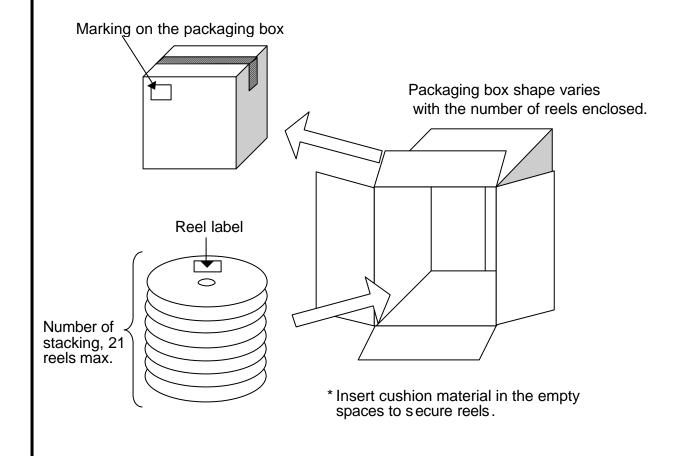
2. Specification

No.	Item	Condition	Remarks
1	Reel outer diameter	Refer to the attachment.	
2	Reel inner diameter	Refer to the attachment.	
3	Reel inner width	Refer to the attachment.	
4	Quantity in a reel	4000 pieces/reel	
5	Taping direction	Tape unreeling direction (with markings facing up)	
6	Top tape attachment position	Top tape 8.0+/-0.2mm Solution Top tape 5.5mm Embossed tape Top tape edge must stay inside the sprocket holes of the embossed carrier (Sprocket holes shall not be covered).	Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g
7	Label attachment position	Tape unreeling direction	Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin
8	Tape leader part and tape ending part	Ending part Product-loaded part Embossed carrier Top tape 200~220mm (Product-unloaded part) 100~150mm, 25~38 pieces worth, (Product-unloaded part) 300~ 400mm	_
9	<u> </u>	No missing products shall be allowed. 21 reels/box (Max)	84000 pieces/box(Max)
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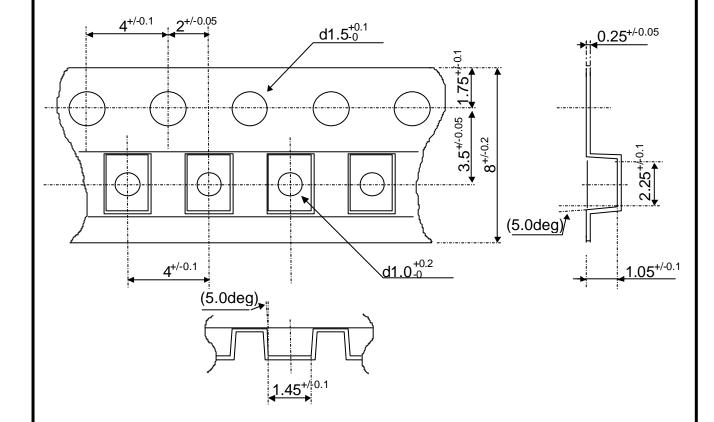
1. Method

- 1) Load products in each cavity of an embossed carrier tape, in the correct orientation, by leaving the product-unloaded part shown in Item No. 8(P9-6) of the packaging specification.
- 2) Heat-seal a top tape in good alignment on the carrier tape.
- 3) After 4000 pieces are loaded and reeled, provide a product-unloaded part at the tape-leader portion. Secure the tip of the carrier tape with a piece of adhesive tape.
- 4) Stack the reels (21 reels max.) and enclose them in a packaging box. Close the flaps with a piece of adhesive tape.
- 5) Provide markings on the packaging box.
 - < Items to be indicated >
 - 1. Part No.
 - 2. Quantity
 - 3. Lot No.
 - 4. Manufacturer name
 - 5. Country of origin



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[Embossed tape dimensions] Unit: mm



<Remarks>

- (1) Unspecified corner radius shall be 0.3mm max.
- (2) Cumulative pitch error of sprocket holes shall be +/-0.2mm for 10 pitches.

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